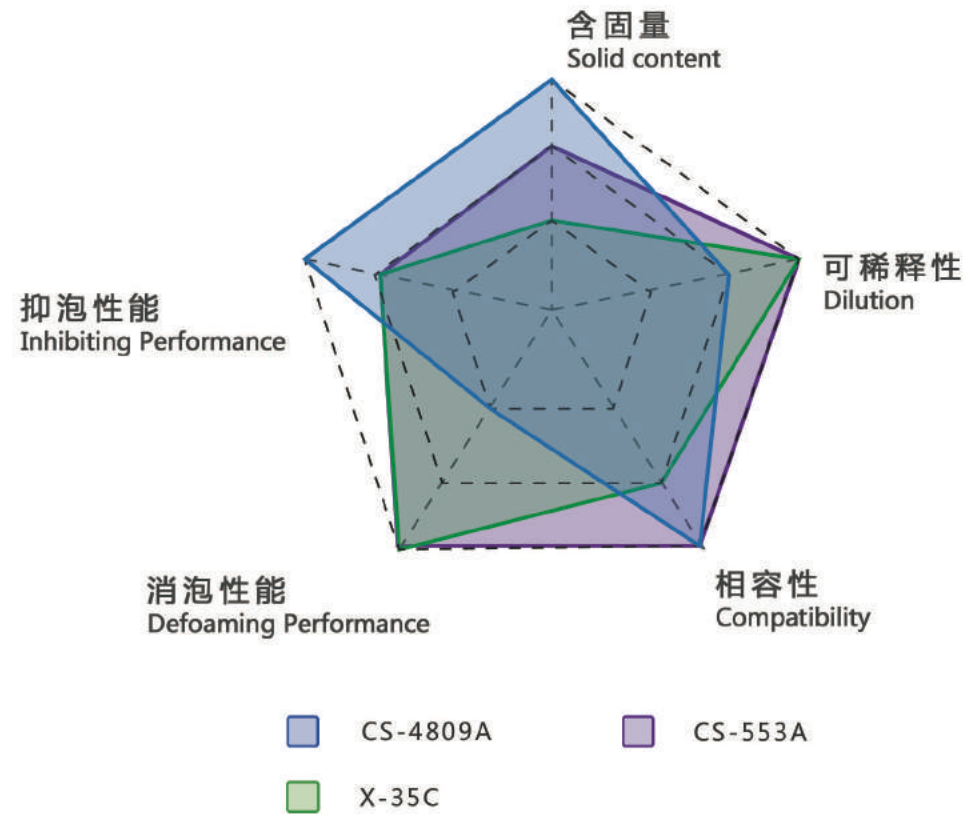


消泡剂 在工业清洗行业 中的应用



电路板清洗 CIRCUIT BOARD CLEANING

起泡物
Foaming substance :

皂化物、碱液、清洗剂等 ;
Saponification, lye, cleaning agents, etc ;

起泡环境
Foaming circumstance :

需要添加消泡剂的工序主要是内层线路制作工序中的曝光、显影及蚀刻、去膜工序。该工序由于化学反应及搅拌产生大量气泡，极大的影响清洗设备的效率。其中，曝光、显影工序用到的助剂是稀碱溶液(常用的是1%~2%的碳酸钠水溶液，温度30℃~40℃)，用于与光致抗蚀干膜中未曝光部分的活性基团(羧基)反应，生成可溶于水的物质及二氧化碳气体；蚀刻、去膜工序用到的助剂是强碱溶液(NaOH浓度一般为3%~5%，温度50℃~60℃)，将蚀铜后仍留在线路铜上的干膜去掉；

Mainly in the inner line production section of the exposure, development and etching, stripping process. The process produce a large number of bubbles because of chemical reactions and mixing, which cause a great impact on the efficiency of cleaning equipment. And the ingredients of using in process of exposure and developing is a dilute alkali solution (commonly used 1% ~ 2% of the aqueous solution of sodium carbonate, temperature is 30 °C ~ 40 °C), (Carboxyl group) reacts with the active group (carboxyl group) in the unexposed part of the photoresist film to form water-soluble substances and carbon dioxide gas; the auxiliary agent used in the etching and film removal process is a strong alkali solution (NaOH concentration is generally 3% to 5%, the temperature is 50 °C ~ 60 °C), the solution will remove the retained dry film on the copper. ;

四新最优推荐
First recommendation :

CS-4809A ;
CS-553A ;
X-35C ;

其次推荐
Second recommendation :

S-2080 ;
CS-245 ;

添加点
Adding point :

添加在清洗槽中 ;
Add in the cleaning tank ;

添加方式
Adding method :

间歇添加 ;
Intermittent addition ;

注意事项
Notes :

高含量乳液及硅聚醚类产品如果要稀释，最好是用增稠水稀释；
If preferring to dilute before using, it's better to dilute by thicker water for defoamers with higher solid content or silicone polyether type ;
CS-245存储和运输都要按照我司的规定；
The storage and transportation of CS-245 should be according to SIXIN regulation ;

参考用量
Reference dosage :

0.5‰~5‰ ;